Interfacing the DP8420A/21A/22A to the National Semiconductor NS32332

I INTRODUCTION

This application note describes how to interface the National Semiconductor NS32332 microprocessor to the DP8422A DRAM controller (also applicable to DP8420A/21A). There are four designs shown in this application note. The differences between these designs are as follows:

- Design #1 can be used up to 14 MHz, has no wait states in normal accesses and no wait states in burst accesses, does not contain an MMU unit, is programmed with DTACK0 out of the DP8422A, and has the 1W input of the PAL tied high,
- 2. Design #2 can be used up to 15 MHz, has one wait state in normal accesses and no wait states in burst accesses, does not contain an MMU unit, is programmed with $\overline{\text{DTACK1}}$ out of the DP8422A, and has the $\overline{1W}$ input of the PAL tied high,
- 3. Design #3 can be used up to 14 MHz, has one wait state in normal accesses and no wait states in burst accesses, does contain an MMU unit, is programmed with DTACK0 out of the DP8422A, and has the 1W input of the PAL tied high,
- 4. Design #4 can be used up to 15 MHz, has two wait states in normal accesses and no wait states in burst accesses, does contain an MMU unit, is programmed with $\overline{\text{DTACK1}}$ out of the DP8422A, and has the $\overline{1W}$ input of the PAL tied high,

An extra wait state can also be added to any of the four above designs by tying the $\overline{1W}$ input low. It is assumed that the reader is already familiar with NS32332 and the DP8422A modes of operation.

II DESCRIPTION OF FOUR DESIGNS, ALLOWING UP TO 15 MHz OPERATION WITH 0, 1, OR 2 WAIT STATES IN NORMAL ACCESSES, NO WAIT STATES IN BURST ACCESSES AND AN OPTIONAL MMU (MEMORY MANAGEMENT UNIT, NS32382)

These four designs are all similar. Taken together they allow the user to design a 32332 DRAM system with 0, 1, or 2 wait states during an access. This system can be designed with or without the NS32382 MMU. These designs are shown driving two banks of DRAM, each bank being 32 bits in width, giving a maximum memory capacity of 32 Mbytes (using 4 Mbit x 1 DRAMs). By choosing a different RAS and \overline{CAS} configuration mode (see programming mode bits section of DP8422A data sheet), this application could support 4 banks of DRAM, giving a memory capacity of 64 Mbytes (using 4 Mbit x 1 DRAMs).

Note: When driving 64 Mbytes, the timing calculations will have to be adjusted to the greater capacitive load.

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National Semiconductor Application Note 543 Webster (Rusty) Meier Jr. and Joe Tate November 1987



The memory banks are interleaved on every four word (32bit word) boundary. This means that the address bit (A4) is tied to the bank select input of the DP8422A (B1). If the majority of accesses made by the NS32332 are sequential, the NS32332 can be doing burst accesses most of the time. Each burst of four words can alternate memory banks, allowing one memory bank to be precharging (RAS precharge) while the other bank is being accessed. This is a higher performance memory system than a non-interleaved memory system (bank select on the higher address bits). Each back to back memory access to the same memory bank will generally require extra wait states to be inserted into the CPU access cycles to guarantee the $\overline{\text{RAS}}$ precharge time.

The logic shown in this application note forms a complete NS32332 memory sub-system, no other logic is needed. This sub-system automatically takes care of:

- A. arbitration between Port A, Port B, and refreshing the DRAM;
- B. the isertion of wait states to the processor (Port A and Port B) when needed (i.e., if RAS precharge is needed, refresh is happening during a memory access, the other Port is currently doing an access . . . etc.);
- C. performing byte writes and reads to the 32-bit words in memory.

By making use of the enable input on the 74AS373 latch, this application can easily be used in a dual access application. The addresses and chip select are TRI-STATE® through this latch, the write input (WIN), lock input (\overline{LOCK}), and $\overline{CAS0}$ -3 inputs must also be able to be TRI-STATE (a 74AS244 could be used for this purpose). By multiplexing the above inputs (through the use of the above parts and similar parts for Port B), the DP8422A can be used in a dual access applications. All the timing (see TIMING section of this application note) will remain the same whether single or dual accessing is implemented.

If an MMU (NS32382) is used the signal "PAV" should be input to the PAL " \overline{ADS} " input instead of the NS32332 \overline{ADS} input. If wanted the user could input the \overline{MADS} signal to the PAL (using the "NC1" input), allowing the access cycle to be started one clock earlier. When the PAL senses the \overline{MADS} input transitioning low it can insert one less wait state into that particular access.

The PAL output term $\overline{D1}$ and the input term $\overline{1W}$ can be deleted from the PAL if the user is not interested in adding an extra wait state to any of the four designs.

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III NS32332 DESIGN, UP TO 15 MHz WITH 0, 1, OR 2 WAIT STATES IN NORMAL ACCESSES AND NO WAIT STATES IN BURST ACCESSES, PROGRAMMING MODE BITS

Programming Bits	Description	
R0 = 0	RAS Low Two Clocks, RAS	
R1 = 1	Precharge of Two Clocks	4
R2 = X	Choose depending on whether design	
R3 = X	1-4 is chosen. Choose R2,3 = 0,0 if	
	DTACK0 is wanted. Choose R2,3 =	
	1,0 if DTACK1 is wanted (DTACK low	
	first rising CLK edge after access RAS	5
	is low).	C
R4 = 0	No WAIT states during burst accesses	
R5 = 0		6
R6 = 0	If $WAITIN = 0$, add one clock to	
	DTACK. Since we are not using the	
	WAITIN input it should be tied high on	7
	the DP8422A. Select DTACK	
R7 = 1 R8 = 1	Non-interleaved mode	
$R_0 = 1$ R9 = X	Non-intelleaved mode	
H9 — X		
C0 = X	Select based upon the input	
C1 = X	"DELCLK" frequency. Example: if the	8
C2 = X	input clock frequency is 14 MHz then	0
C3 = X	choose C0,1,2, $=$ 1,1,0 (divide by	
	seven, this will give a frequency of 2 MHz).	
C4 = 0	RAS groups selected by "B1". This	
$C_{4} = 0$ $C_{5} = 0$	mode allows two RAS outputs to go	
C6 = 1	low during an access, and allows byte	
	writing 32-bit words.	
C7 = 1	Column address setup time of 0 ns	g
C8 = 1	Row address hold time of 15 ns	5
C9 = 1	Delay CAS during write accesses to	
	one clock after RAS transitions low	
B0 = 1	Fall-thru latches	
B1 = 0	Access mode 0	
$\overline{ECAS}0 = 0$	CAS not extended beyond RAS	
0 = program with low	-	1
1 = program with high	voltage level	

X = program with either high or low voltage level (don't care condition)

IV NS32332, DESIGN #2 (NO MMU UNIT) AT 15 MHz WITH ONE WAIT STATE IN NORMAL ACCESSES, DESIGN #4 (HAS MMU UNIT) AT 15 MHz WITH TWO WAIT STATES IN NORMAL ACCESSES. DESIGNS #2 AND #4 HAVE A TOTAL OF THREE CLOCK PERIODS TO ACCESS THE DRAM IN NORMAL ACCESSES AND HAVE ZERO WAIT STATES DURING BURST ACCESSES.

1. Maximum time to latch enable valid: ADS makes the 74AS373 fall-thru at 17 ns (max) from

PHI1 CLOCK low + 5 ns (74AS04) + 2 ns (PHI1 to CTTL clock skew) = 24 ns

*Note: MADS and PAV are valid 17 ns maximum from PHI1 rising clock edge if NS32382 is used

 2. Maximum time to address valid from CTTL CLOCK (NS32332 spec) = 20 ns (address valid from PHI1 clock) + 2 ns (PHI1 to CTTL clock skew) = 22 ns
 Maximum time to latched address valid from CTTL CLOCK:
11.5 ns (74AS373 enable time maximum) + 24 ns (#1) = 35.5 ns
 Minimum ALE high setup time to CLOCK high (DP8422A- 25 needs 15 ns):
66.6 ns (one clock period) $-$ 17 ns (NS32332 max time to ADS low from PHI1) $-$ 2 ns (PHI1 to CTTL clock skew) - 15 ns (PAL16R6B combinational output) $-$ 5 ns (74AS04) $=$ 27.6 ns
5. Minimum address setup time to CLOCK high (DP8422A- 25 needs 18 ns):
66.6 ns (one clock period) $-$ 35.5 ns (#3) $=$ 31.1 ns
6. Minimum CS setup time to CLOCK high (DP8422A-25 needs 13 ns):
66.6 ns (one clock period) $-$ 35.5 ns (#3) $-$ 9 ns (Max 74AS138 decoder) $=$ 22.1 ns
 Determining t_{RAC} (RAS access time required by the DRAM):
199.8 ns (three clock periods to do access) -2 ns (NS32C201 PHI1 to CTTL clock skew) -7 ns (data set- up time) -7 ns (74F245) -26 ns (CLK to RAS low on DP8422A-25) $=$ 157.8 ns. Therefore the t _{RAC} of the DRAM must be 157.8 ns or less.
 Determining t_{CAC} (CAS access time) and column address access time required by the DRAM:
199.8 ns $- 2$ ns $- 7$ ns $- 7$ ns $- 12$ ns (74AS32, 6 ns, plus 6 ns extra, taken from lab data on the 74AS32, requried to drive a 22 Ω damping resistor and an equivalent load capacitance of 150 pF, approximately 16 DRAM CAS inputs per CASGn output) $- 72$ ns (CLK to CAS low on DP8422A-25) = 99.8 ns. Therefore the t _{CAC} of the DRAM must be 99.8 ns or less.
 Determining the nibble mode access time required by the DRAM:
66.6 ns (T3 clock) - 2 ns (clock skew) - 12 ns (PAL16R6B, CASEN clocked output) - 12 ns (74AS32, see #8 description) - 7 ns (74F245) - 7 ns (data setup) = 26.6 ns Therefore the nibble mode access time needed by the
DRAM must be 26.6 ns or less.
10. Maximum time to DTACK0 low (PAL16R6B needs 15 ns setup to CTTL):
66.6 ns (one clock) - 33 ns (DTACK0 low from CLK high on DP8422A-25) = 33.6 ns **Note that DTACK1 may be used from some of the designs, it occurs at 28 ns maximum from the CLK input.
 Minimum RDY setup time to RDY being sampled (12 ns to the PHI1 falling edge is needed by the NS32332):
27.3 ns (minimum PHI1 high pulse width) – 2 ns (NS32C201 PHI1 to CTTL clock skew) – 12 ns (PAL16R6B clocked output maximum) = 13.3 ns
*Note: Calculations can be performed for different frequencies and the oth- er designs (#1 and #3) by substituting the appropriate values into the above equations. Design numbers 1 and 3 have only two clock periods to perform an access, therefore the t _{RAC} and t _{CAC} calcula- tions would be affected by having one less clock period during an access.

PAL16R6B CTTL /CS /ADS /BOUT /DTACK EXRDY /1W RESET NC1 GND /OE /EN_TRAN NC2 /AREQ /CASEN /D2 /D1 RDY /ADSL VCC IF (VCC) /ADSL = /ADS

+/ADSL*AREQ*/RESET +/ADSL*/BOUT*/CS +/ADSL*/CASEN*/CS

- IF (VCC) /EN=_TRAN = /AREQ*/CS*/CASEN +/EN_TRAN*/BOUT
- RDY := /CS*/ADSL*D1*/1W
 +/CS*/ADSL*DTACK*D2*1W
- /D1 := /DTACK*D1*/1W*/CS*/RESET
 +*/EXRDY*CS*/1W
- /D2 := /CS*/D1*/1W*/RESET +/CS*/DTACK*D2*1W*/RESET +CS*/EXRDY*1W*/RESET
- /CASEN := /ADSL*D2*/RESET +AREQ*/RESET

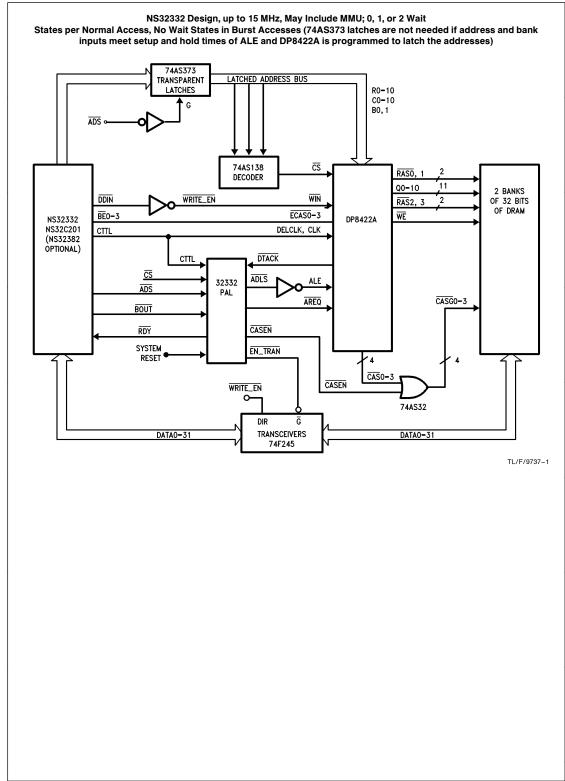
/AREQ := /ADSL*/RESET

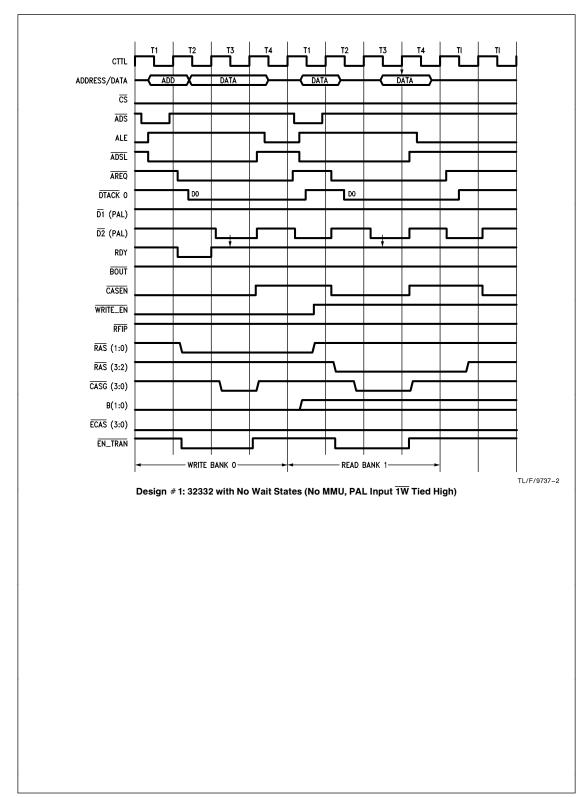
Key: Reading PAL[®] Equations Written in PLAN™

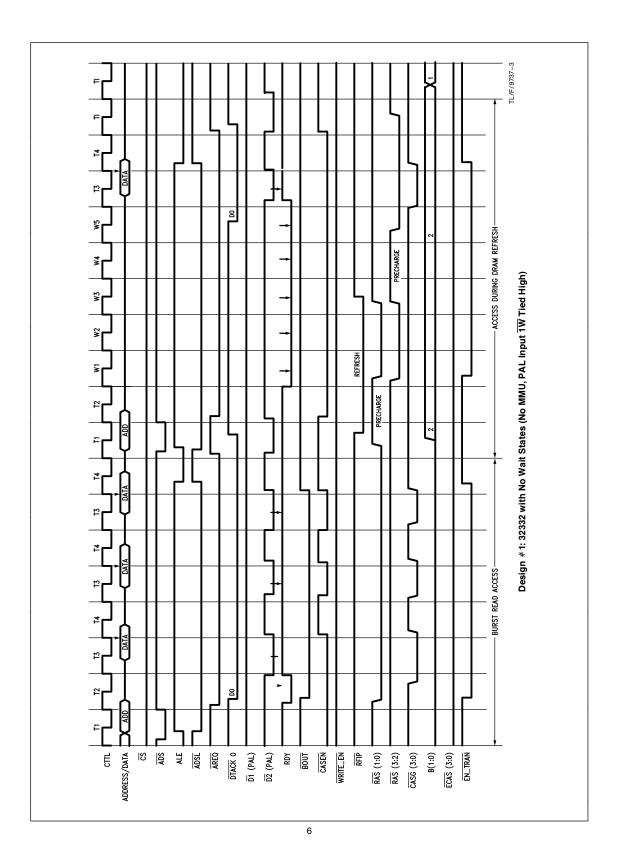
EXAMPLE EQUATIONS: /CASEN := /ADSL*D2*/RESET +AREQ*/RESET

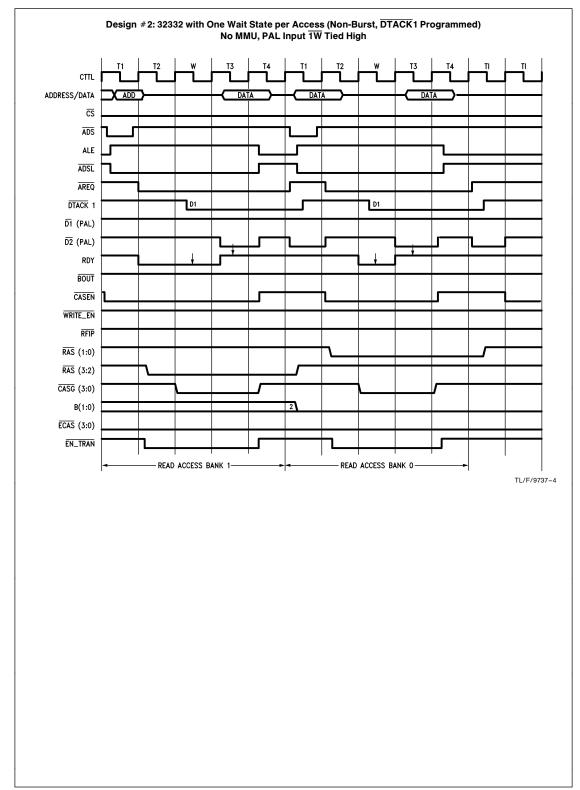
This example reads: the output "/CASEN" will transition low on the next rising "CTTL" clock edge (given that one of the following conditions are valid a setup time before "CTTL" transitions high);

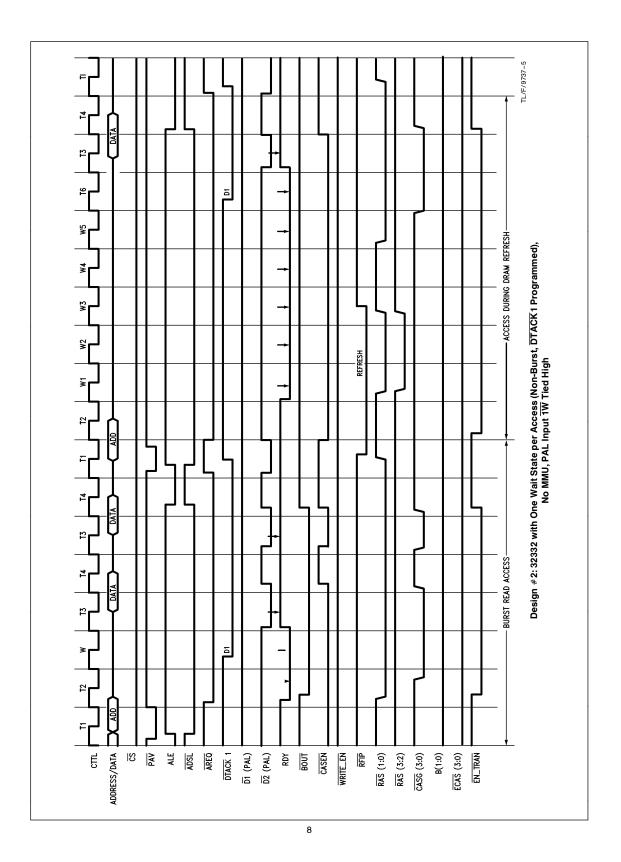
- 1. the output "/ADSL" is low AND the output "/D2" is high AND the input "RESET" is low, OR
- 2. the output "/AREQ" is high AND the input "RESET" is low

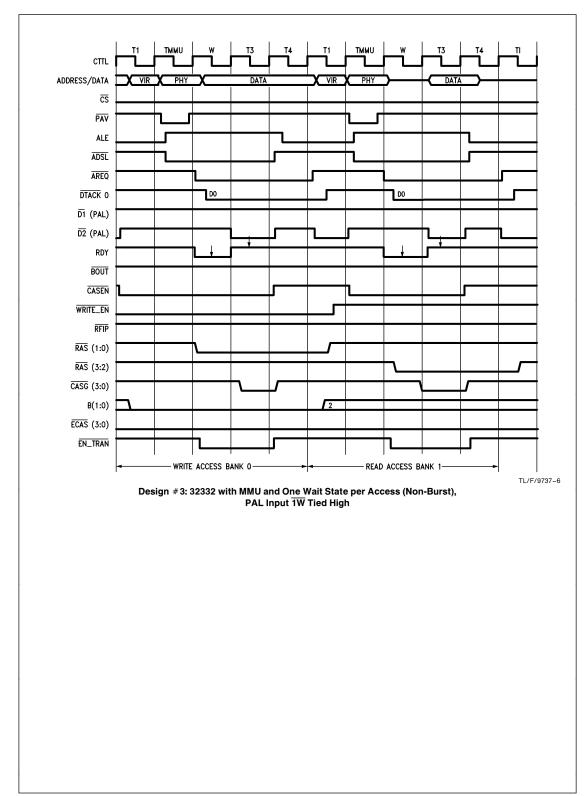


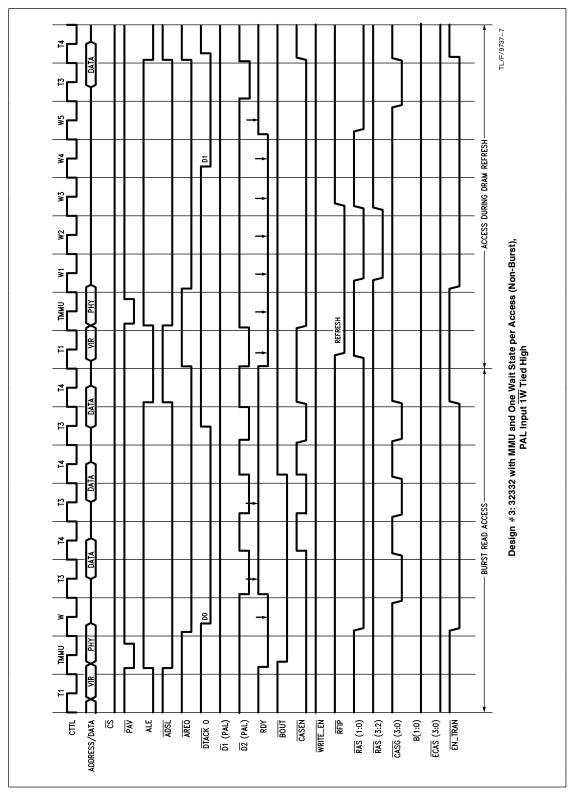


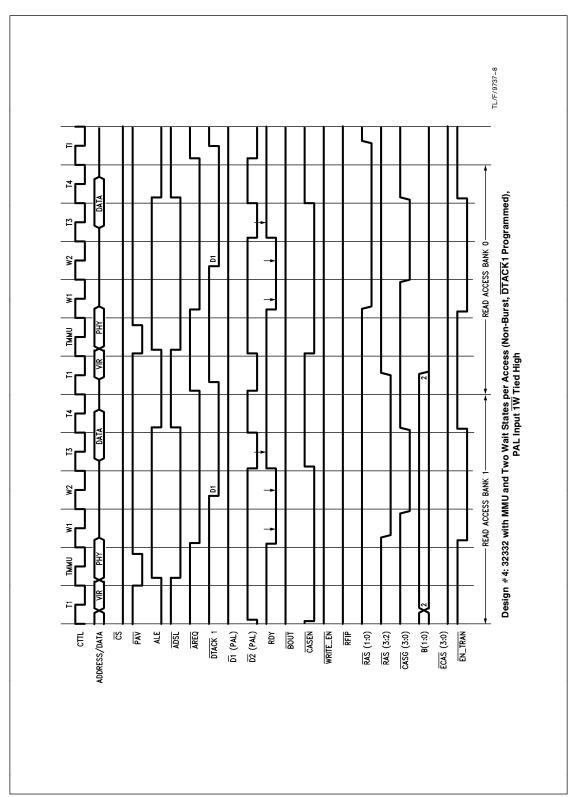


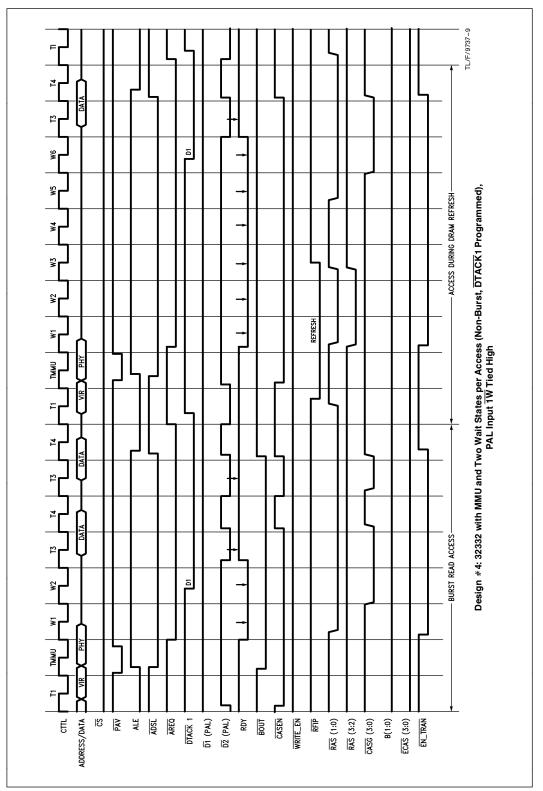


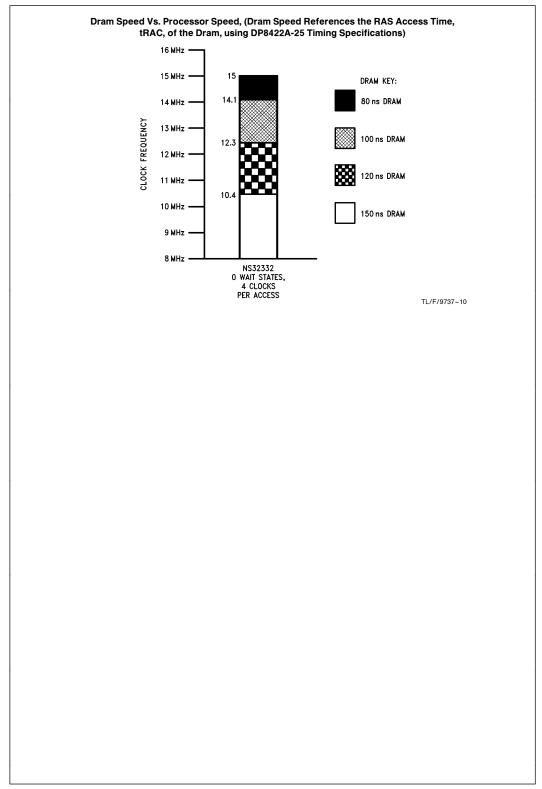












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